



BUK92150-55A

N-channel TrenchMOS logic level FET

12 June 2014

Product data sheet

1. General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

2. Features and benefits

- Low conduction losses due to low on-state resistance
- Q101 compliant
- Suitable for logic level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

3. Applications

- 12 V and 24 V loads
- Automotive and general purpose power switching
- Motors, lamps and solenoids

4. Quick reference data

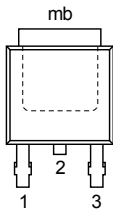
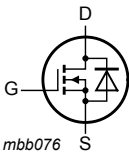
Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|---|-----|-----|-----|------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}; T_j \leq 175\text{ °C}$ | - | - | 55 | V |
| I_D | drain current | $V_{GS} = 5\text{ V}; T_{mb} = 25\text{ °C};$ Fig. 2 ; Fig. 3 | - | - | 11 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C};$ Fig. 1 | - | - | 36 | W |
| Static characteristics | | | | | | |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = 10\text{ V}; I_D = 5\text{ A}; T_j = 25\text{ °C}$ | - | 97 | 125 | mΩ |
| | | $V_{GS} = 5\text{ V}; I_D = 5\text{ A}; T_j = 175\text{ °C};$ Fig. 11 ; Fig. 12 | - | - | 280 | mΩ |
| | | $V_{GS} = 4.5\text{ V}; I_D = 5\text{ A}; T_j = 25\text{ °C}$ | - | - | 155 | mΩ |
| | | $V_{GS} = 5\text{ V}; I_D = 5\text{ A}; T_j = 25\text{ °C};$ Fig. 11 ; Fig. 12 | - | 120 | 140 | mΩ |
| Dynamic characteristics | | | | | | |
| Q_{GD} | gate-drain charge | $V_{GS} = 5\text{ V}; I_D = 5\text{ A}; V_{DS} = 44\text{ V};$ $T_j = 25\text{ °C};$ Fig. 13 | - | 2.6 | - | nC |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------------|--|---|-----|-----|-----|------|
| Avalanche ruggedness | | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $I_D = 11\text{ A}$; $V_{sup} \leq 55\text{ V}$; $R_{GS} = 50\ \Omega$; $V_{GS} = 5\text{ V}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; unclamped | - | - | 16 | mJ |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-----------------------------------|---|---|
| 1 | G | gate |  <p>DPAK (SOT428)</p> |  <p>mbb076</p> |
| 2 | D | Drain | | |
| 3 | S | source | | |
| mb | D | mounting base; connected to drain | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-----------------|---------|---|---------|
| | Name | Description | Version |
| BUK92150-55A | DPAK | plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) | SOT428 |
| BUK92150-55A/CD | DPAK | plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) | SOT428 |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-----------------|--------------|
| BUK92150-55A | 9215055A |
| BUK92150-55A/CD | |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|----------|----------------------|--|-----|-----|------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ }^\circ\text{C}$; $T_j \leq 175\text{ }^\circ\text{C}$ | - | 55 | V |

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------------|--|--|-----|-----|------|
| V _{DGR} | drain-gate voltage | R _{GS} 20 kΩ | - | 55 | V |
| V _{GS} | gate-source voltage | | -15 | 15 | V |
| P _{tot} | total power dissipation | T _{mb} = 25 °C; Fig. 1 | - | 36 | W |
| I _D | drain current | T _{mb} = 25 °C; V _{GS} = 5 V; Fig. 2 ; Fig. 3 | - | 11 | A |
| | | T _{mb} = 100 °C; V _{GS} = 5 V; Fig. 3 | - | 7.8 | A |
| I _{DM} | peak drain current | T _{mb} = 25 °C; pulsed; t _p ≤ 10 μs; Fig. 2 | - | 44 | A |
| T _{stg} | storage temperature | | -55 | 175 | °C |
| T _j | junction temperature | | -55 | 175 | °C |
| Source-drain diode | | | | | |
| I _S | source current | T _{mb} = 25 °C | - | 11 | A |
| I _{SM} | peak source current | pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C | - | 44 | A |
| Avalanche ruggedness | | | | | |
| E _{DS(AL)S} | non-repetitive drain-source avalanche energy | I _D = 11 A; V _{sup} ≤ 55 V; R _{GS} = 50 Ω; V _{GS} = 5 V; T _{j(init)} = 25 °C; unclamped | - | 16 | mJ |

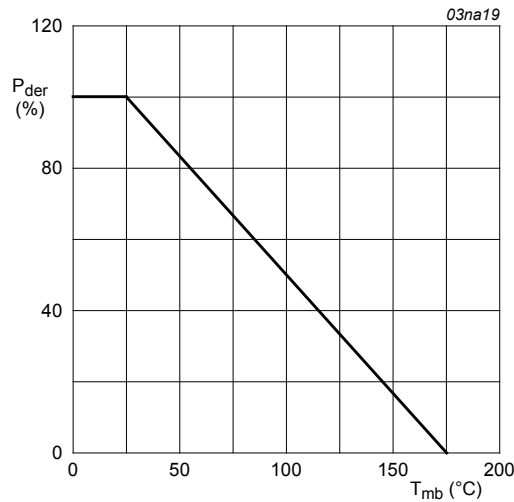


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100\%$$

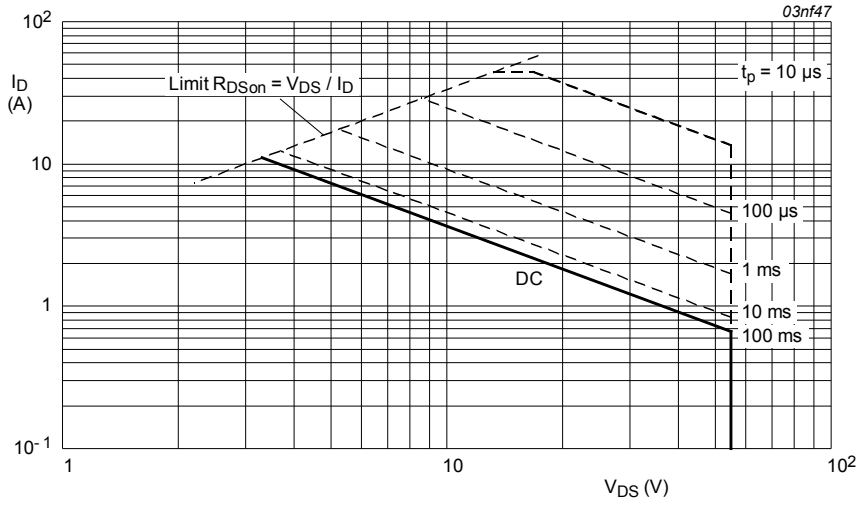


Fig. 2. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$T_{mb} = 25^\circ C; I_{DM}$ is single pulse

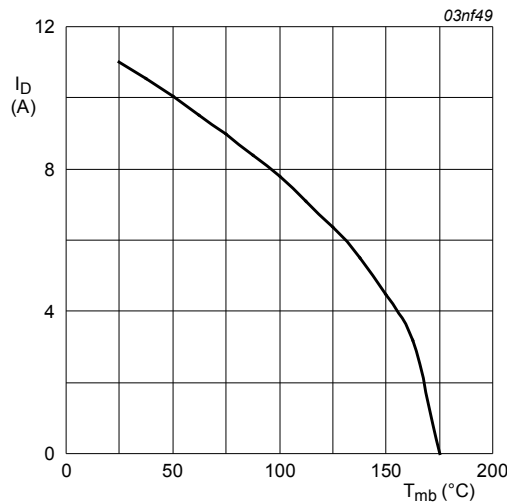


Fig. 3. Continuous drain current as a function of mounting base temperature

$$V_{GS} \geq 4.5V I_{der} = \frac{I_D}{I_{D(25^\circ C)}} \times 100\%$$

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|---|------------|-----|------|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | Fig. 4 | - | - | 4.1 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | | - | 71.4 | - | K/W |

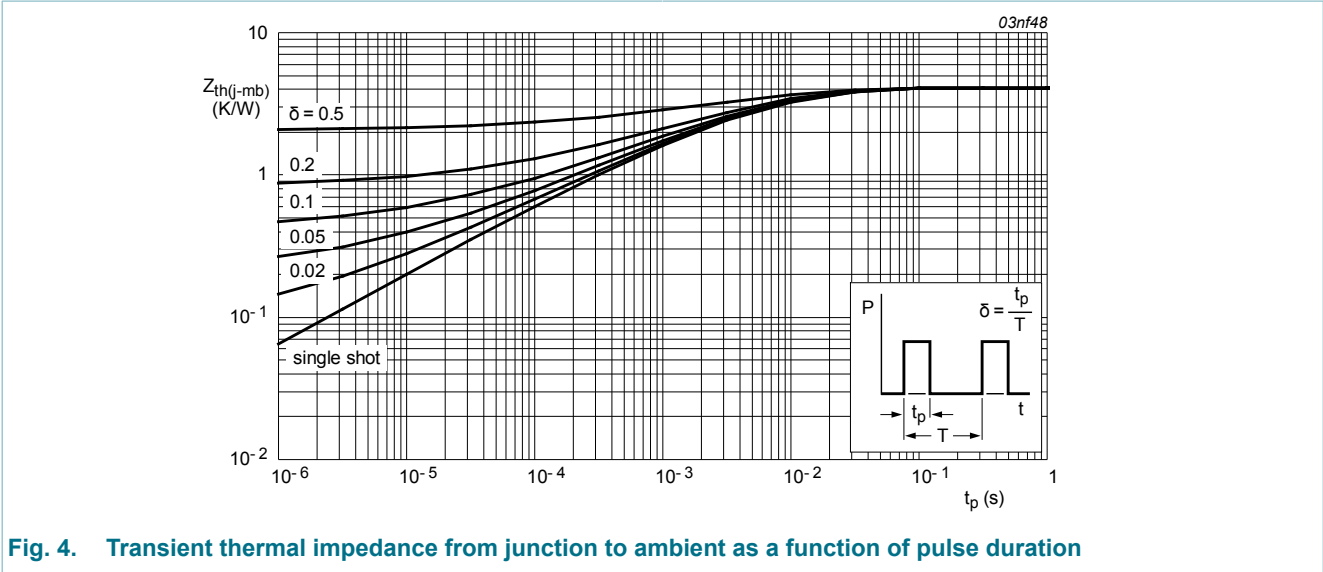


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|---|-----|------|-----|---------------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | 55 | - | - | V |
| | | $I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ }^\circ\text{C}$ | 50 | - | - | V |
| $V_{GS(th)}$ | gate-source threshold voltage | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ\text{C};$ Fig. 10 | - | - | 2.3 | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C};$ Fig. 10 | 1 | 1.5 | 2 | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ }^\circ\text{C};$ Fig. 10 | 0.5 | - | - | V |
| I_{DSS} | drain leakage current | $V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 175 \text{ }^\circ\text{C}$ | - | - | 500 | μA |
| | | $V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 0.05 | 10 | μA |
| I_{GSS} | gate leakage current | $V_{GS} = 10 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 2 | 100 | nA |
| | | $V_{GS} = -10 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 2 | 100 | nA |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = 10 \text{ V}; I_D = 5 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$ | - | 97 | 125 | m Ω |
| | | $V_{GS} = 5 \text{ V}; I_D = 5 \text{ A}; T_j = 175 \text{ }^\circ\text{C};$ Fig. 11; Fig. 12 | - | - | 280 | m Ω |
| | | $V_{GS} = 4.5 \text{ V}; I_D = 5 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$ | - | - | 155 | m Ω |
| | | $V_{GS} = 5 \text{ V}; I_D = 5 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ Fig. 11; Fig. 12 | - | 120 | 140 | m Ω |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|------------------------------|--|-----|------|-----|------|
| Dynamic characteristics | | | | | | |
| $Q_{G(\text{tot})}$ | total gate charge | $I_D = 5 \text{ A}; V_{DS} = 44 \text{ V}; V_{GS} = 5 \text{ V};$ $T_j = 25 \text{ }^\circ\text{C};$ Fig. 13 | - | 6 | - | nC |
| Q_{GS} | gate-source charge | | - | 0.76 | - | nC |
| Q_{GD} | gate-drain charge | | - | 2.6 | - | nC |
| C_{iss} | input capacitance | $V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^\circ\text{C};$ Fig. 14 | - | 240 | 338 | pF |
| C_{oss} | output capacitance | | - | 50 | 65 | pF |
| C_{rss} | reverse transfer capacitance | | - | 40 | 58 | pF |
| $t_{d(\text{on})}$ | turn-on delay time | $V_{DS} = 20 \text{ V}; R_L = 3.3 \text{ } \Omega; V_{GS} = 5 \text{ V};$ $R_{G(\text{ext})} = 10 \text{ } \Omega; T_j = 25 \text{ }^\circ\text{C}$ | - | 8 | - | ns |
| t_r | rise time | | - | 57 | - | ns |
| $t_{d(\text{off})}$ | turn-off delay time | | - | 16 | - | ns |
| t_f | fall time | | - | 13 | - | ns |
| L_D | internal drain inductance | measured from drain to centre of die; $T_j = 25 \text{ }^\circ\text{C}$ | - | 2.5 | - | nH |
| L_S | internal source inductance | measured from source lead to source bond pad; $T_j = 25 \text{ }^\circ\text{C}$ | - | 7.5 | - | nH |
| Source-drain diode | | | | | | |
| V_{SD} | source-drain voltage | $I_S = 15 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C};$ Fig. 15 | - | 0.85 | 1.2 | V |
| t_{rr} | reverse recovery time | $I_S = 20 \text{ A}; di_S/dt = -100 \text{ A}/\mu\text{s};$ $V_{GS} = -10 \text{ V}; V_{DS} = 30 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 24 | - | ns |
| Q_r | recovered charge | | - | 26 | - | nC |

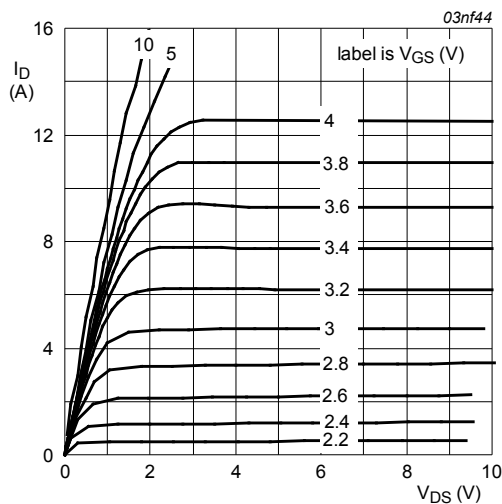


Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values

$T_j = 25^\circ\text{C}$

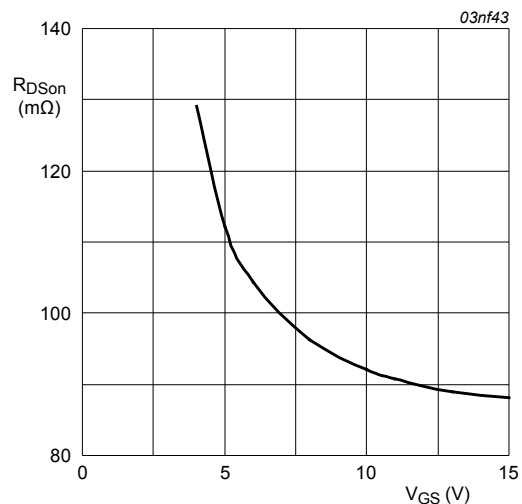
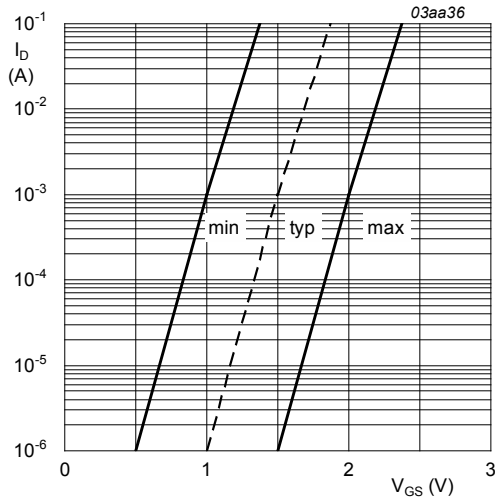


Fig. 6. Drain-source on-state resistance as a function of gate-source voltage; typical values

$T_j = 25^\circ\text{C}; I_D = 5\text{A}$



$T_j = 25\text{ }^\circ\text{C}; V_{DS} = 5\text{ V}$

Fig. 7. Sub-threshold drain current as a function of gate-source voltage

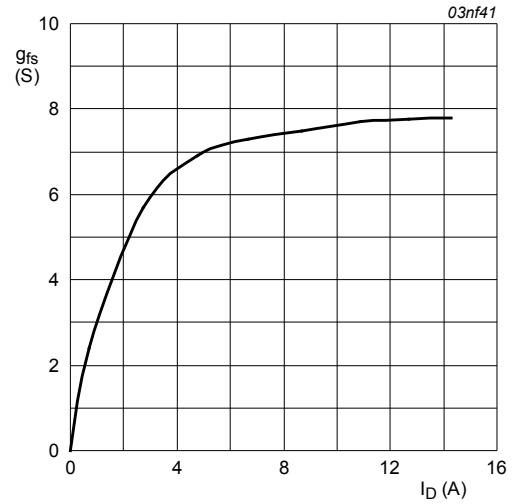


Fig. 8. Forward transconductance as a function of drain current; typical values

$T_j = 25\text{ }^\circ\text{C}; V_{DS} = 25\text{ V}$

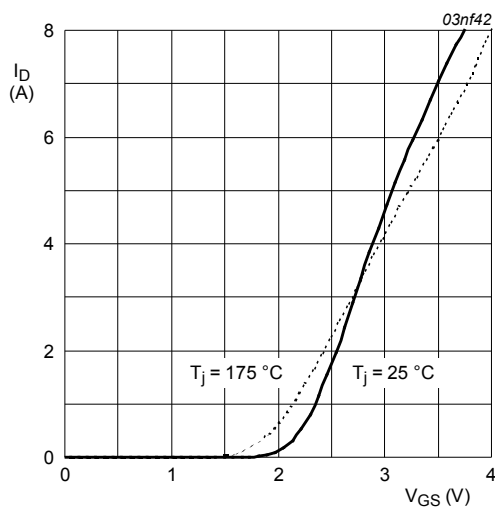


Fig. 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

$V_{DS} = 25\text{ V}$

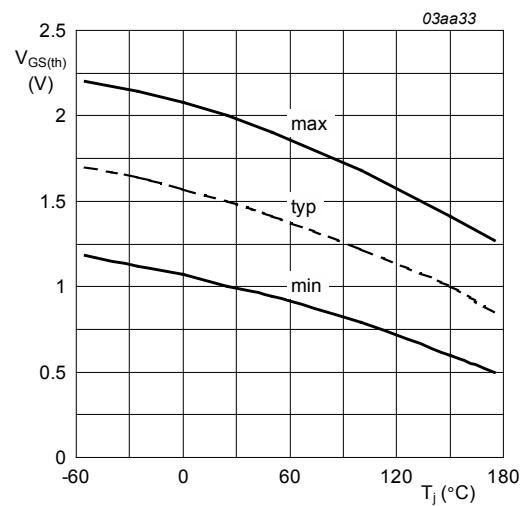


Fig. 10. Gate-source threshold voltage as a function of junction temperature

$I_D = 1\text{ mA}; V_{DS} = V_{GS}$

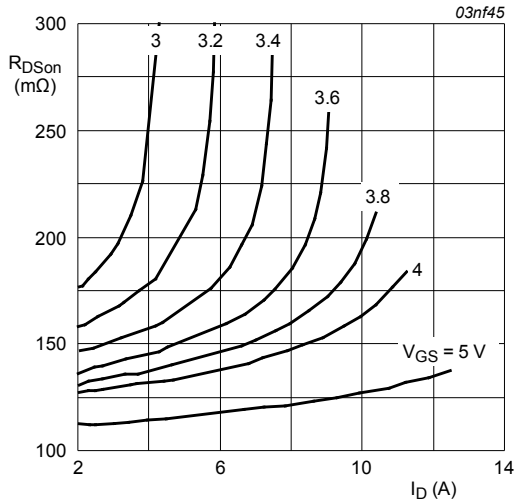


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

$T_j = 25^\circ\text{C}$

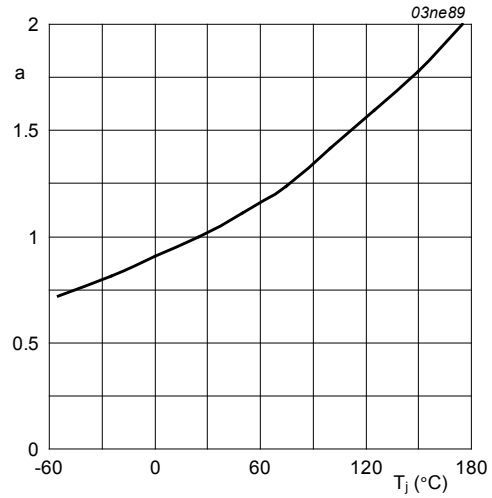


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

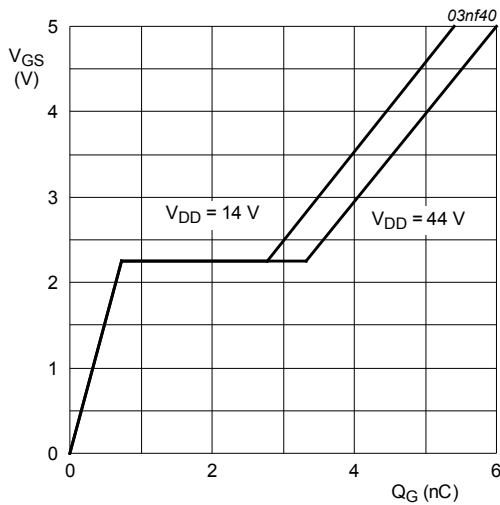


Fig. 13. Gate-source voltage as a function of gate charge; typical values

$T_j = 25^\circ\text{C}; I_D = 5\text{A}$

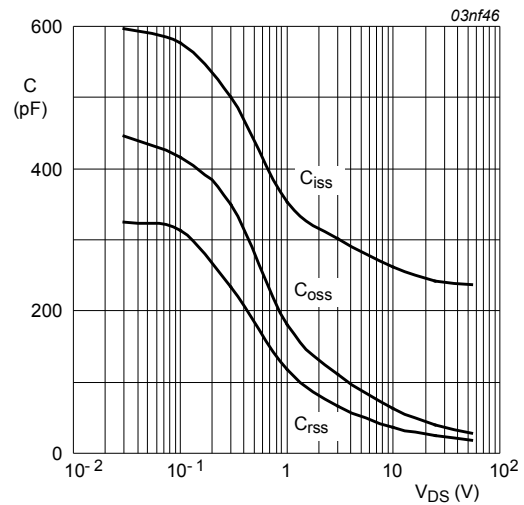


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$V_{GS} = 0\text{V}; f = 1\text{MHz}$

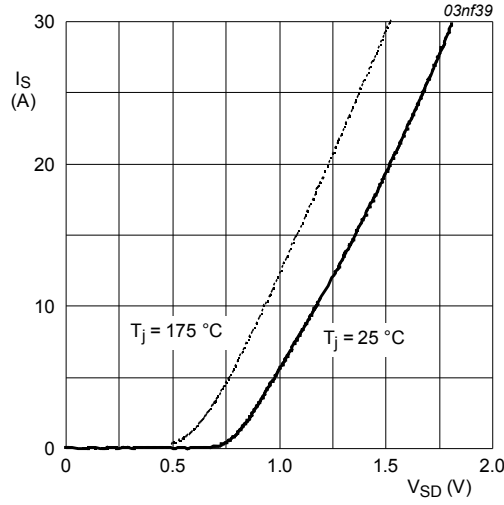
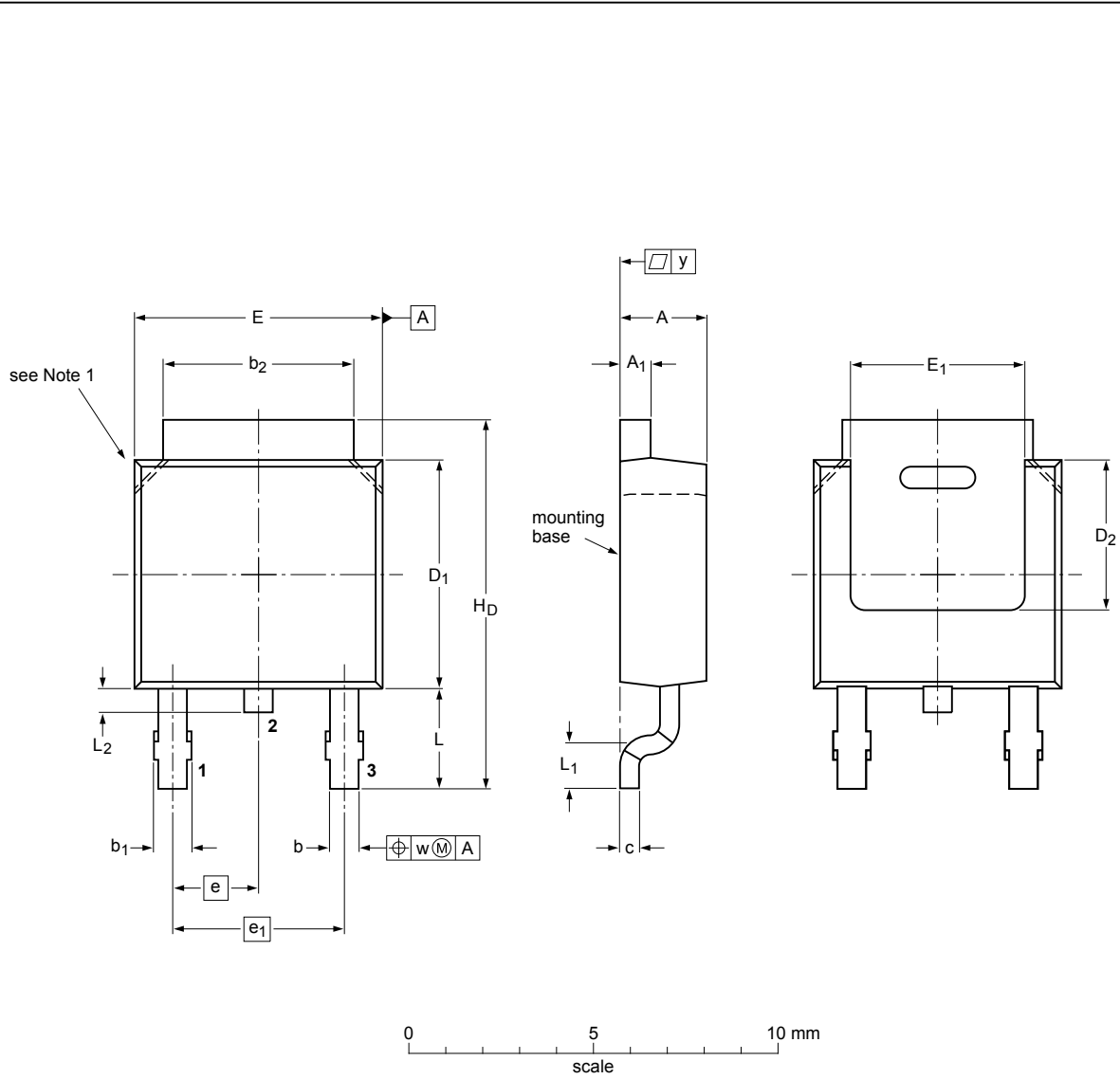


Fig. 15. Reverse diode current as a function of reverse diode voltage; typical values

$$V_{GS} = 0V$$

11. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) SOT428



Dimensions (mm are the original dimensions)

| Unit | A | A ₁ | b | b ₁ | b ₂ | c | D ₁ | D ₂ | E | E ₁ | e | e ₁ | H _D | L | L ₁ | L ₂ | w | y |
|------|-----|----------------|------|----------------|----------------|------|----------------|----------------|-----|----------------|-------|----------------|----------------|------|----------------|----------------|-----|-----|
| mm | max | 2.38 | 0.93 | 0.89 | 1.1 | 5.46 | 0.56 | 6.22 | | 6.73 | | | 10.4 | 2.95 | | 0.9 | | 0.2 |
| | nom | | | | | | | | | | 2.285 | 4.57 | | | | | 0.2 | |
| | min | 2.22 | 0.46 | 0.71 | 0.9 | 5.00 | 0.20 | 5.98 | 4.0 | 6.47 | 4.45 | | 9.6 | 2.55 | 0.5 | 0.5 | | |

Note

1. Plastic body may have 45° chamfer.

sot428_po

| Outline version | References | | | | European projection | Issue date |
|-----------------|------------|--------|-------|--|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT428 | | TO-252 | SC-63 | | | 06-03-16 14-06-10 |

Fig. 16. Package outline DPAK (SOT428)

12. Legal information

12.1 Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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